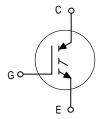
Product Preview Data Sheet

Insulated Gate Bipolar Transistor

N-Channel Enhancement Mode Silicon Gate

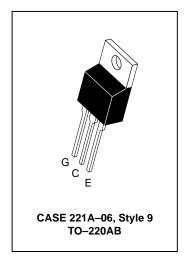
This Insulated Gate Bipolar Transistor (IGBT) uses an advanced termination scheme to provide an enhanced and reliable high voltage blocking capability. Its new 600V IGBT technology is specifically suited for applications requiring both a high temperature short circuit capability and a low VCE(on). It also provides fast switching characteristics and results in efficient operation at high frequencies. This new E–series introduces an Energy–efficient and short circuit rated device.

- Industry Standard TO-220 Package
- High Speed E_{off}: 44 μJ/A typical at 125°C
- High Short Circuit Capability 10 μs minimum at 125°C
- Low On-Voltage 2.0V typical at 3A, 125°C
- Robust High Voltage Termination



MGP5N60E

IGBT IN TO-220
5 A @ 90°C
6 A @ 25°C
600 VOLTS
SHORT CIRCUIT RATED
LOW ON-VOLTAGE



MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit	
Collector–Emitter Voltage	VCES	600	Vdc	
Collector–Gate Voltage ($R_{GE} = 1.0 \text{ M}\Omega$)	VCGR	600	Vdc	
Gate-Emitter Voltage — Continuous	VGE	±20	Vdc	
Collector Current — Continuous @ T _C = 25°C — Continuous @ T _C = 90°C — Repetitive Pulsed Current (1)	I _{C25} I _{C90} I _{CM}	6 5 12	Adc Apk	
Total Power Dissipation @ T _C = 25°C Derate above 25°C	PD	62 0.50	Watts W/°C	
Operating and Storage Junction Temperature Range	T _J , T _{Stg}	-55 to 150	°C	
Short Circuit Withstand Time (V_{CC} = 360 Vdc, V_{GE} = 15 Vdc, T_J = 125°C, R_G = 20 Ω)	t _{SC}	10	μs	
Thermal Resistance — Junction to Case – IGBT — Junction to Ambient	R _θ JC R _θ JA	2.01 65	°C/W	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C	
Mounting Torque, 6–32 or M3 screw	10	10 lbf•in (1.13 N•m)		

⁽¹⁾ Pulse width is limited by maximum junction temperature.

This document contains information on a new product. Specifications and information are subject to change without notice.



MGP5N60E

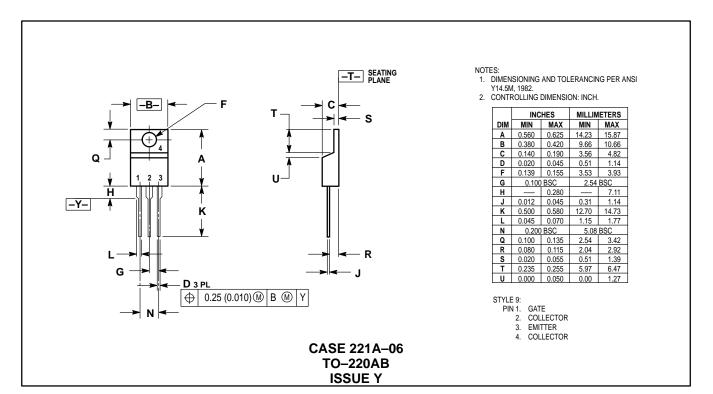
ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Ch	aracteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS		•		•		
Collector–to–Emitter Breakdown \ (V _{GE} = 0 Vdc, I _C = 250 μAdc) Temperature Coefficient (Positiv	· ·	BVCES	600 —	 870	_	Vdc mV/°C
Emitter–to–Collector Breakdown Voltage (V _{GE} = 0 Vdc, I _{EC} = 100 mAdc)		B _{VECS}	15	_	_	Vdc
Zero Gate Voltage Collector Current (VCE = 600 Vdc, VGE = 0 Vdc) (VCE = 600 Vdc, VGE = 0 Vdc, TJ = 125°C)		ICES	=	=	100 2500	μAdc
Gate–Body Leakage Current ($V_{GE} = \pm 20 \text{ Vdc}$, $V_{CE} = 0 \text{ Vdc}$)		IGES	_	_	250	nAdc
ON CHARACTERISTICS (1)						
Collector-to-Emitter On-State Vo (V _{GE} = 15 Vdc, I _C = 1.5 Adc) (V _{GE} = 15 Vdc, I _C = 1.5 Adc, T (V _{GE} = 15 Vdc, I _C = 3 Adc)		VCE(on)	_ _ _	1.58 1.46 2.02	2.06 — 2.77	Vdc
Gate Threshold Voltage (V _{CE} = V _{GE} , I _C = 1 mAdc) Threshold Temperature Coeffici	ent (Negative)	VGE(th)	4.0 —	6.0 10	8.0 —	Vdc mV/°C
Forward Transconductance (VCE	= 10 Vdc, I _C = 3 Adc)	9fe	_	1.3	_	Mhos
DYNAMIC CHARACTERISTICS		•				
Input Capacitance		C _{ies}	_	362	_	pF
Output Capacitance	(V _{CE} = 25 Vdc, V _{GE} = 0 Vdc, f = 1.0 MHz)	C _{oes}	_	36	_	
Transfer Capacitance	, ,	C _{res}	_	3	_	
SWITCHING CHARACTERISTICS	(1)					
Turn-On Delay Time	(Vac - 360)/do lo - 3 Ado	td(on)	_	tbd	_	ns
Rise Time	(V _{CC} = 360 Vdc, I _C = 3 Adc, V _{GE} = 15 Vdc, L = 300 μ H R _G = 20 Ω , T _J = 25°C) Energy losses include "tail"	t _r	_	tbd	_	
Turn-Off Delay Time		td(off)	_	60	_	
Fall Time		t _f	-	218	-	
Turn-Off Switching Loss		E _{off}	_	0.09	0.14	mJ
Turn-On Delay Time	$(V_{CC}=360~Vdc,~I_{C}=3~Adc,~V_{GE}=15~Vdc,~L=300~\mu H$ R _G = 20 Ω, T _J = 125°C) Energy losses include "tail"	^t d(on)	_	tbd	_	ns
Rise Time		t _r	_	tbd	_]
Turn-Off Delay Time		td(off)	_	tbd	_	1
Fall Time		t _f	_	tbd	_	
Turn-Off Switching Loss		E _{off}	-	0.13	<u> </u>	mJ
Gate Charge		QT	_	14	_	nC
	$V_{CC} = 360 \text{ Vdc}, I_{C} = 3 \text{ Adc},$ $V_{GE} = 15 \text{ Vdc})$	Q ₁	_	6	_	1
		Q ₂	_	4	_	
INTERNAL PACKAGE INDUCTAN	CE					
Internal Emitter Inductance (Measured from the emitter lead 0.25" from package to emitter bond pad)		LE		7.5	_	nH

⁽Measured from the emitter lead 0.25" from package
(1) Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

2 Motorola IGBT Device Data

PACKAGE DIMENSIONS



Motorola IGBT Device Data 3

MGP5N60E

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and (A) are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

How to reach us:

USA/EUROPE: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036. 1–800–441–2447

MFAX: RMFAX0@email.sps.mot.com – TOUCHTONE (602) 244–6609 INTERNET: http://Design-NET.com

JAPAN: Nippon Motorola Ltd.; Tatsumi–SPD–JLDC, Toshikatsu Otsuki, 6F Seibu–Butsuryu–Center, 3–14–2 Tatsumi Koto–Ku, Tokyo 135, Japan. 03–3521–8315

HONG KONG: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park, 51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852–26629298



